



#### **Features**

- High speed
  □ 15 ns
- Output enable (OE) feature
- CMOS for optimum speed/power
- Low active power ☐ 633 mW
- Low standby power ☐ 110 mW
- TTL-compatible inputs and outputs
- Automatic power-down when deselected

#### **Functional Description**

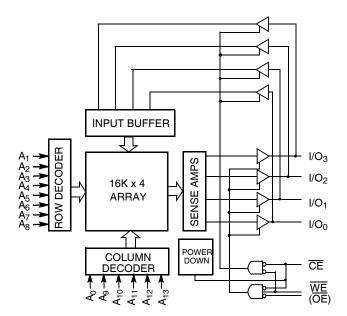
The CY7C166 is a high-performance CMOS static RAMs organized as 16,384 by 4 bits. Easy memory expansion is provided by an active LOW Chip Enable ( $\overline{\text{CE}}$ ) and tri-state drivers. The CY7C166 has an active LOW Output Enable ( $\overline{\text{OE}}$ ) feature. This device has an automatic power-down feature, reducing the power consumption by 65% when deselected.

Writing to the device <u>is accomplished</u> when the Chip Enable  $(\overline{CE})$  and Write Enable  $(\overline{WE})$  inputs are both LOW (and the Output Enable  $(\overline{OE})$  is LOW). Data on the four input/output pins  $(I/O_0$  through  $I/O_3$ ) is written into the memory location specified on the address pins  $(A_0$  through  $A_{13}$ ).

Reading the device is accomplished by taking Chip Enable  $(\overline{CE})$  LOW (and  $\overline{OE}$  LOW), while Write Enable (WE) remains HIGH. Under these conditions the contents of the memory location specified on the address pins will appear on the four data I/O pins.

The I/O pins stay in a high-impedance state when Chip Enable (CE) is HIGH (or Output Enable (OE) is HIGH). A die coat is used to insure alpha immunity.

## **Logic Block Diagram**





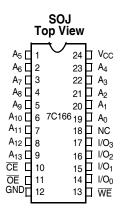
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# **Pin Configuration**



#### **Selection Guide**

Description	CY7C166-15
Maximum Access Time (ns)	15
Maximum Operating Current (mA)	115
Maximum CMOS Standby Current (mA)	20



## **Maximum Ratings**

Exceeding the maximum ratings may impair the useful life of the device. These user guidelines are not tested.

Ambient temperature with Supply voltage to ground potential .....-0.5 V to +7.0 V DC voltage applied to outputs in high Z  $\rm State^{[1]}$  ......–0.5 V to +7.0 V DC input voltage<sup>[1]</sup>.....-0.5 V to +7.0 V

Output current into outputs (LOW)	20 mA
Static discharge voltage(per MIL-STD-883, method 3015)	. > 2001 V
Latch-up current	> 200 mA

# **Operating Range**

Range	Ambient Temperature	V <sub>CC</sub>
Commercial	0 °C to +70 °C	5 V ± 10%

#### **Electrical Characteristics**

Over the Operating Range

			-15		
Parameter	Description	Test Conditions	Min	Max	Unit
V <sub>OH</sub>	Output HIGH voltage	V <sub>CC</sub> = Min, I <sub>OH</sub> = -4.0 mA	2.4	-	V
V <sub>OL</sub>	Output LOW voltage	V <sub>CC</sub> = Min, I <sub>OL</sub> = 8.0 mA	-	0.4	V
V <sub>IH</sub>	Input HIGH voltage		2.2	V <sub>CC</sub>	V
V <sub>IL</sub>	Input LOW voltage <sup>[1]</sup>		-0.5	0.8	V
I <sub>IX</sub>	Input leakage current	$GND \le V_I \le V_{CC}$	-5	+5	μА
I <sub>OZ</sub>	Output leakage current	$GND \le V_O \le V_{CC}$ , output disabled	-5	+5	μА
I <sub>CC</sub>	V <sub>CC</sub> operating supply current	V <sub>CC</sub> = Max, I <sub>OUT</sub> = 0 mA	-	115	mA
I <sub>SB1</sub>	Automatic CE power-down current <sup>[2]</sup>	Max V <sub>CC</sub> , <del>CE</del> ≥ V <sub>IH</sub> Min Duty Cycle = 100%	_	40	mA
I <sub>SB2</sub>	Automatic CE power-down current <sup>[2]</sup>	$\begin{aligned} &\text{Max V}_{\text{CC}}, \overline{\text{CE}} \geq \text{V}_{\text{CC}} - 0.3 \text{ V}, \\ &\text{V}_{\text{IN}} \geq \text{V}_{\text{CC}} - 0.3 \text{ V or V}_{\text{IN}} \leq 0.3 \text{ V} \end{aligned}$	_	20	mA

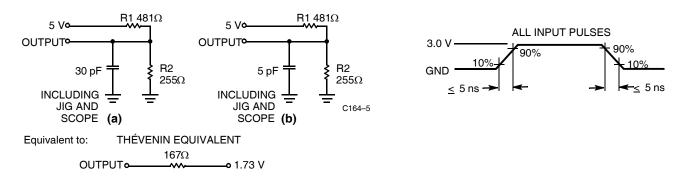
# Capacitance<sup>[3]</sup>

Parameter	Description	Test Conditions	Max	Unit
C <sub>IN</sub>	Input capacitance	$T_A = 25 ^{\circ}\text{C}, f = 1 \text{MHz},$	10	pF
C <sub>OUT</sub>	Output capacitance	V <sub>CC</sub> = 5.0 V	10	pF

- 1. Minimum voltage is equal to -3.0 V for pulse durations less than 30 ns.
- A pull-up resistor to V<sub>CC</sub> on the CE input is required to keep the device deselected during V<sub>CC</sub> power-up, otherwise I<sub>SB</sub> will exceed values given.
   Tested initially and after any design or process changes that may affect these parameters.



#### **AC Test Loads and Waveforms**



#### **Switching Characteristics**

Over the Operating Range<sup>[4]</sup>

		CY7C	166-15	
Parameter	Description	Min	Max	Unit
READ CYCLE	·		•	
t <sub>RC</sub>	Read cycle time	15	_	ns
t <sub>AA</sub>	Address to data valid	_	15	ns
t <sub>OHA</sub>	Output hold from address change	3	_	ns
t <sub>ACE</sub>	CE LOW to data valid	_	15	ns
t <sub>DOE</sub>	OE LOW to data valid	_	10	ns
t <sub>LZOE</sub>	OE LOW to low Z	3	_	ns
t <sub>HZOE</sub>	OE HIGH to high Z	_	8	ns
t <sub>LZCE</sub>	CE LOW to low Z <sup>[5]</sup>	3	_	ns
t <sub>HZCE</sub>	CE HIGH to high Z <sup>[5, 6]</sup>	_	8	ns
t <sub>PU</sub>	CE LOW to power-up	0	_	ns
t <sub>PD</sub>	CE HIGH to power-down	_	15	ns
WRITE CYCLE <sup>[7]</sup>	•			
t <sub>WC</sub>	Write cycle time	15	_	ns
t <sub>SCE</sub>	CE LOW to write end	12	_	ns
t <sub>AW</sub>	Address set-up to write end	12	_	ns
t <sub>HA</sub>	Address hold from write end	0	_	ns
t <sub>SA</sub>	Address set-up to write start	0	_	ns
t <sub>PWE</sub>	WE pulse width	12	_	ns
t <sub>SD</sub>	Data set-up to write end	10	-	ns
t <sub>HD</sub>	Data hold from write end	0	-	ns
t <sub>LZWE</sub>	WE HIGH to low Z <sup>[5]</sup>	5	_	ns
t <sub>HZWE</sub>	WE LOW to high Z <sup>[5, 6]</sup>	_	7	ns

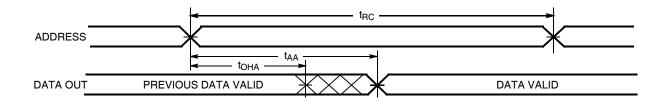
#### Notes

Test conditions assume signal transition time of 5 ns or less, timing reference levels of 1.5 V, input pulse levels of 0 to 3.0 V, and output loading of the specified loudness.
 At any given temperature and voltage condition, t<sub>HZCE</sub> is less than t<sub>LZCE</sub> for any given device. These parameters are guaranteed by design and not 100% tested.
 t<sub>HZCE</sub> and t<sub>HZWE</sub> are specified with C<sub>L</sub> = 5 pF as in part (b) in AC Test Loads. Transition is measured ±500 mV from steady-state voltage.
 The internal write time of the memory is defined by the overlap of CE LOW and WE LOW. Both signals must be LOW to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.

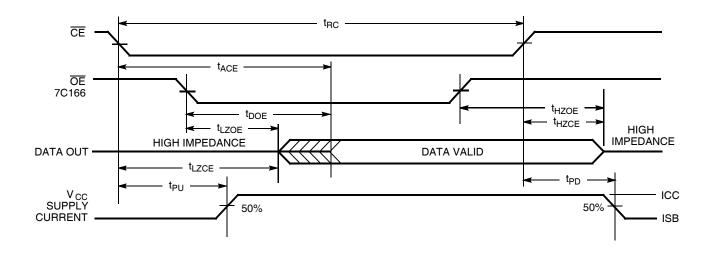


# **Switching Waveforms**

# Read Cycle No. 1<sup>[8, 9]</sup>



## Read Cycle No. 2<sup>[8, 10]</sup>

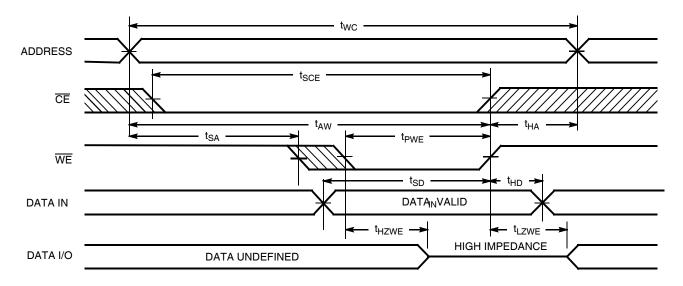


<sup>8.</sup> WE is HIGH for read cycle.
9. Device is continuously selected,  $\overline{CE} = V_{\parallel ...}(CY7C166: \overline{OE} = V_{\parallel L} \text{ also}).$ 10. Address valid prior to or coincident with  $\overline{CE}$  transition LOW.

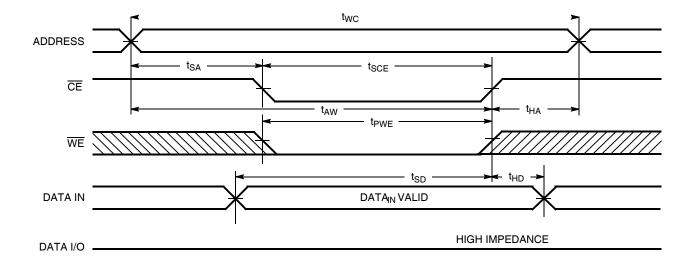


## Switching Waveforms (continued)

# Write Cycle No. 1(WE Controlled)[11,12]



# Write Cycle No. 2(CE Controlled)[11,12,13]



#### Notes

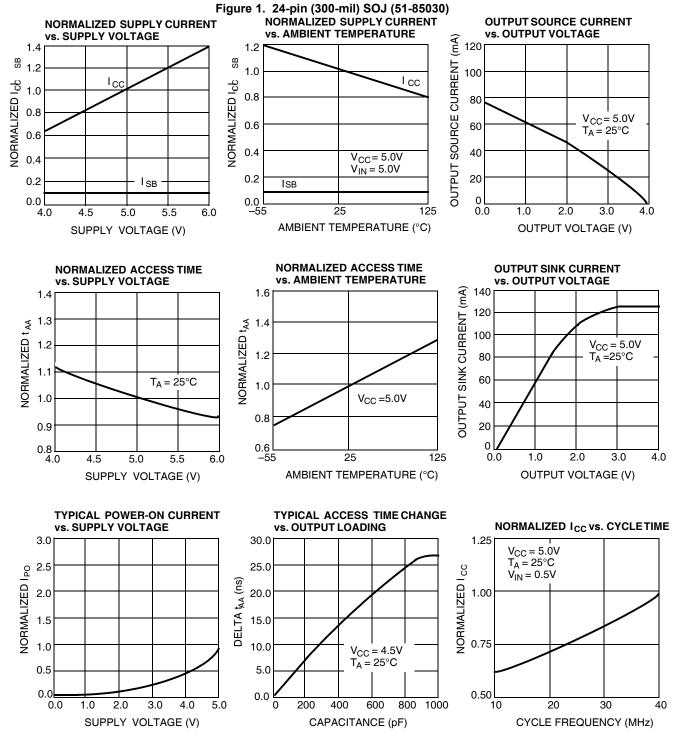
<sup>11.</sup> The internal write time of the memory is defined by the overlap of  $\overline{\text{CE}}$  LOW and  $\overline{\text{WE}}$  LOW. Both signals must be LOW to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.

12. C Y7C166 only: Data I/O will be high-impedance if  $\overline{\text{OE}} = \text{V}_{\text{IH}}$ .

13. If  $\overline{\text{CE}}$  goes HIGH simultaneously with  $\overline{\text{WE}}$  HIGH, the output remains in a high-impedance state.



# Typical DC and AC Characteristics





#### **CY7C166 Truth Table**

CE	WE	OE	Input/Output	Mode	Power
Н	Х	Х	High Z	Deselect/power-down	Standby (I <sub>SB</sub> )
L	Н	L	Data out	Read	Active (I <sub>CC</sub> )
L	L	Н	Data in	Write	Active (I <sub>CC</sub> )
L	Н	Н	High Z	Select/output disabled	Active (I <sub>CC</sub> )

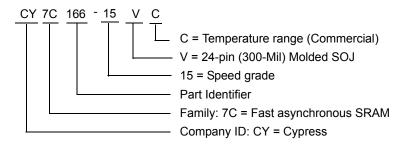
# **Address Designators**

Address Name	Address Function	CY7C166 Pin Number
A5	Х3	1
A6	X4	2
A7	X5	3
A8	X6	4
A9	X7	5
A10	Y5	6
A11	Y4	7
A12	Y0	8
A13	Y1	9
A0	Y2	19
A1	Y3	20
A2	X0	21
A3	X1	22
A4	X2	23

# **Ordering Information**

Speed (ns)	Ordering Code	Package Diagram	Package Type	Operating Range
15	CY7C166-15VC	51-85030	24-pin (300-Mil) Molded SOJ	Commercial

# **Ordering Code Definitions**

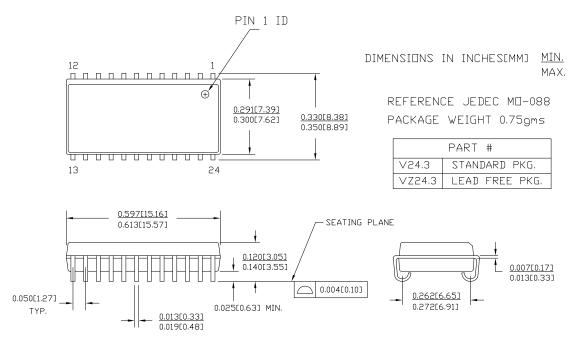


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# **Package Diagram**

Figure 1. 24-pin (300-mil) SOJ, 51-85030



51-85030 \*C

# **Acronyms**

Acronym	Description
CMOS	complementary metal oxide semiconductor
CE	chip enable
DIP	dual inline package
I/O	input/output
OE	output enable
SRAM	static random access memory
SOJ	small outline J-lead
TTL	transistor-transistor logic
WE	write enable

### **Document Conventions**

#### **Units of Measure**

Symbol	Unit of Measure		
ns	nano seconds		
V	Volts		
μA	micro Amperes		
mA	milli Amperes		
mV	milli Volts		
mW	milli Watts		
pF	pico Farad		
°C	degree Celcius		
W	Watts		
%	percent		



# **Document History Page**

Document Title: CY7C166 16 K × 4 Static RAM Document Number: 38-05025					
REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change	
**	106811	09/10/01	SZV	Change from Spec number: 38-00032 to 38-05025	
*A	486744	See ECN	NXR	Removed 20 ns and 35 ns speed bin from Product offering Removed 24-pin (300-Mil) Molded DIP package Changed the description of I <sub>IX</sub> from Input Load Current to Input Leakage Current in DC Electrical Characteristics table Removed I <sub>OS</sub> parameter from DC Electrical Characteristics table Updated the ordering information table	
*B	2894113	03/17/2010	VKN	Added Table of Contents Removed CY7C164 part from the data sheet Removed 25 ns speed bin Removed 22-pin (300-Mil) PDIP package Updated ordering Information Table Updated Package Diagram (Figure 1) Added Sales, Solutions, and Legal Information	
*C	3096933	11/29/2010	PRAS	Added Ordering Code Definitions. Added Acronyms and Units of Measure. Minor edits.	



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